

# TRIPLE ELEMENT THYRISTOR OVERVOLTAGE PROTECTORS

# TISP70xxL1 (VLV) OvervoltageProtectors

# Three Terminal Very Low Voltage (VLV) Protection Ion-Implanted Breakdown Region

Device	V <sub>DRM</sub> V	V <sub>(BO)</sub>
'7015L1	8	15
'7038L1	28	38

## **Protection for Signal, Data and Control Lines**

- ISDN
- T1/E1
- Ethernet
- RS232 & RS485

### **Low Capacitance**

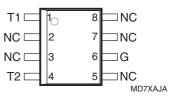
- '7015L1	 24 p	)F	typ.
- '7038L1	 17 p	)F	typ.

### **Rated for International Surge Wave Shapes**

Voltage	Standard	I <sub>PPSM</sub>
Waveshape	Standard	Α
2/10	GR-1089-CORE	200
1.2/50	IEC 61000-4-5	100
10/700	TIA/EIA-IS-968	50
10/700	ITU-T K.20/45/21	50
10/1000	GR-1089-CORE	30

#### 

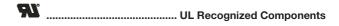
## D Package (Top View)



NC - No internal connection

## **Device Symbol**





### Description

The TISP70xxL1 series are 3-point overvoltage protectors designed for protecting against metallic (transverse mode) and simultaneous longitudinal (common mode) impulses. Each terminal pair has the same voltage limiting values and surge current capability.

These devices are designed to limit overvoltages between signal, data and control port conductors, connected to terminals T1 and T2, and a protective ground, G. Each terminal pair has a symmetrical voltage-triggered bidirectional thyristor characteristic (Figure 1). Overvoltages are initially clipped by breakdown clamping until the voltage rises to the breakover level, which causes the device to crowbar into a low-voltage on state. This low-voltage on state causes the current resulting from the overvoltage to be safely diverted through the device. The device holding current will normally be higher than the available short circuit d.c. system current, causing the protector to switch off as the diverted current subsides.

## How To Order

Device	Package	Carrier	For Standard Termination Finish Order As	For Lead Free Termination Finish Order As
TISP7015L1	D (8-pin, Small-outline)	R (Embossed Tape Reeled)	TISP7015L1DR	TISP7015L1DR-S
HSF/013L1	D (0-pin, Smail-outline)	Tube	TISP7015L1D	TISP7015L1D-S
TISP7038L1	D (8-pin, Small-outline)	R (Embossed Tape Reeled)	TISP7038L1DR	TISP7038L1DR-S
113F / U30L1	D (6-pin, Small-outline)	Tube	TISP7038L1D	TISP7038L1D-S

<sup>\*</sup>RoHS Directive 2002/95/EC Jan 27 2003 including Annex JULY 2000 – REVISED FEBRUARY 2005

BOURNS

The TISP70xxL1 is guaranteed to withstand the listed international ESD (ElectroStatic Discharge), and lightning impulses in both polarities. Terminals marked NC do not have any internal connections and may be left floating or tied to some circuit point. The TISP7038L1 is a functional replacement for the TPN3021.

# Absolute Maximum Ratings, T<sub>J</sub> = 25 °C (Unless Otherwise Noted)

Rating	Symbol	Value	Unit
Repetitive peak off-state voltage TISP7015L1 TISP7038L1	V <sub>DRM</sub>	± 8 ± 28	V
Non-repetitive peak on-state pulse current (see Notes 1 and 2)			
2/10 (Telcordia GR-1089-CORE, 2/10 voltage wave shape)		200	
1/20 (ITU-T K.22, 1.2/50 voltage wave shape, also VDE0878)		100	
8/20 (IEC 61000-4-5, Figure 12 generator, 1.2/50 voltage wave shape)		100	Α
10/160 (TIA/EIA-IS-968 (formally FCC Part 68), 10/160 voltage wave shape)	I <sub>PPSM</sub>	75	^
5/310 (ITU-T k.20/21, 10/700 voltage wave shape, also IEC 61000-4-5 and VDE0433)		50	
10/560 (TIA/EIA-IS-968 (formally FCC Part 68), 10/560 voltage wave shape)		40	1
10/1000 (Telcordia GR-1089-CORE, 10/1000 voltage wave shape)		30	
Non-repetitive peak on-state current (see Note 1)			
16.7 ms (60 Hz) full sine wave		9	
20 ms (50 Hz) full sine wave	I <sub>TSM</sub>	8	Α
0.2 s 50 Hz/60 Hz a.c.		3	
2.0 s 50 Hz/60 Hz a.c.		1.5	
Junction temperature		-40 to +150	°C
Storage temperature range	T <sub>stg</sub>	-65 to +150	°C

- NOTES: 1. Initially the TISP70xxL1 must be in thermal equilibrium at the specified TA. The surge may be repeated after the TISP70xxL1 returns to its initial conditions.
  - 2. These non-repetitive rated currents are peak values of either polarity.

# EMC Immunity Test Ratings, $T_A = 25$ °C (Unless Otherwise Noted)

Rating	Symbol	Value	Unit
Level 3 open-circuit voltage, IEC 61000-4-2, 2001-4, ESD generator, also ITU-T K.20			
contact discharge air discharge	V <sub>O/C</sub>	6 8	kV

# Electrical Characteristics, T<sub>J</sub> = 25 °C (Unless Otherwise Noted)

	Parameter	Test Conditions		Тур	Max	Unit
I <sub>DRM</sub>	Repetitive peak off- state current	$V_D = \pm V_{DRM}$			±4	μΑ
V <sub>(BO)</sub>	Breakover voltage	$dv/dt = \pm 250 \text{ V/ms}, \text{ R}_{\mbox{SOURCE}} = 300 \ \Omega$ TISP701: TISP703:			±15 ±38	V
I <sub>(BO)</sub>	Breakover current	dv/dt = $\pm 250$ V/ms, R <sub>SOURCE</sub> = 300 $\Omega$			±300	mA
I <sub>H</sub>	Holding current	$IT = \pm 5 \text{ A, di/dt} = \pm 30 \text{ mA/ms}$	±30			mA

# **BOURNS**®

# Electrical Characteristics, $T_J$ = 25 $^{\circ}$ C (Unless Otherwise Noted) (Continued)

	Parameter	Test Conditions		Min	Тур	Max	Unit
	Off state conscitores	f 1 MH = V . 1 V rms V = 0 (see Note 2)	TISP7015L1		24		pF
CKA	Off-state capacitance	$f = 1 \text{ MHz}, V_d = 1 \text{ V rms}, V_D = 0 \text{ (see Note 3)}$	TISP7038L1		17		ρı

NOTE 3: Value for any terminal pair, three-terminal guarded measurement with zero voltage bias on the unmeasured terminal.

## **Thermal Characteristics**

	Parameter	Test Conditions	Min	Тур	Max	Unit
$R_{\Theta JA}$	Junction to free air thermal resistance	P <sub>tot</sub> = 0.8 W, T <sub>A</sub> = 25 °C, 5 cm <sup>2</sup> , FR4 PCB			170	°C/W

# **Parameter Measurement Information**

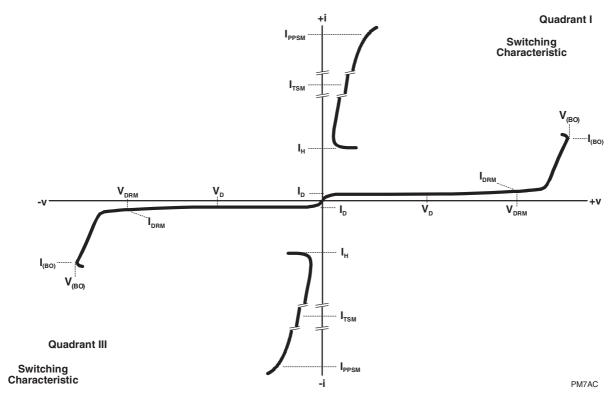


Figure 1. Voltage-Current Characteristic for any Terminal Pair

## **Typical Characteristics**

# 

## Figure 2.

50

 $T_{\rm A}$  - Ambient Temperature -  $^{\circ}{\rm C}$ 

100

150

# ON-STATE CURRENT VS ON-STATE VOLTAGE 100 t<sub>w</sub> = 100 μs - T<sub>A</sub> = 25 °C - T<sub>A</sub> =

Figure 4.

# NORMALIZED BREAKOVER VOLTAGE vs

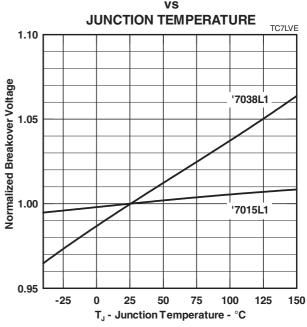


Figure 3.

# NORMALIZED HOLDING CURRENT

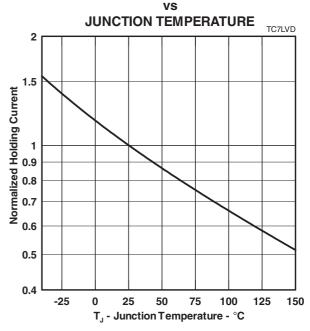


Figure 5.

# **BOURNS®**

# **Typical Characteristics**

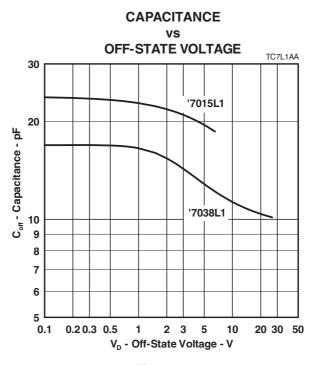


Figure 6.

# **Rating and Thermal Information**

# NON-REPETITIVE PEAK ON-STATE CURRENT

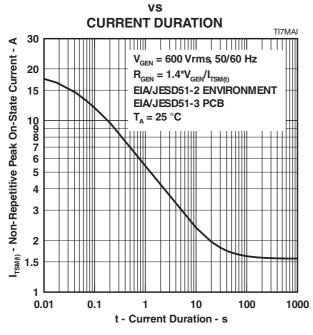


Figure 7.

# **V**<sub>DRM</sub> **DERATING FACTOR**

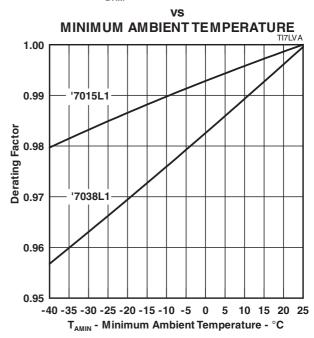


Figure 8.

# BOURNS

# **MECHANICAL DATA**

# **Device Symbolization Code**

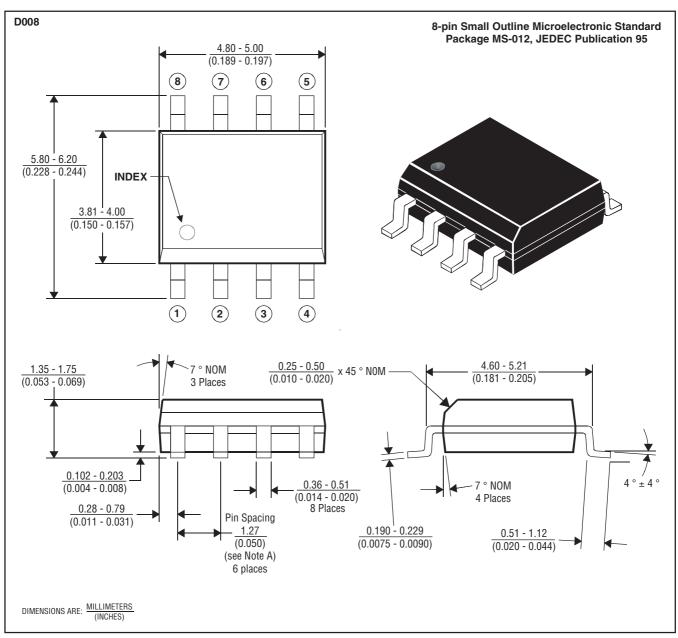
Devices will be coded as below.

Device	Symbolization Code
TISP7015L1	7015L1
TISP7038L1	7038L1

## **MECHANICAL DATA**

## **D008 Plastic Small-outline Package**

This small-outline package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



MDXXAAE

NOTES: A. Leads are within 0.25 (0.010) radius of true position at maximum material condition.

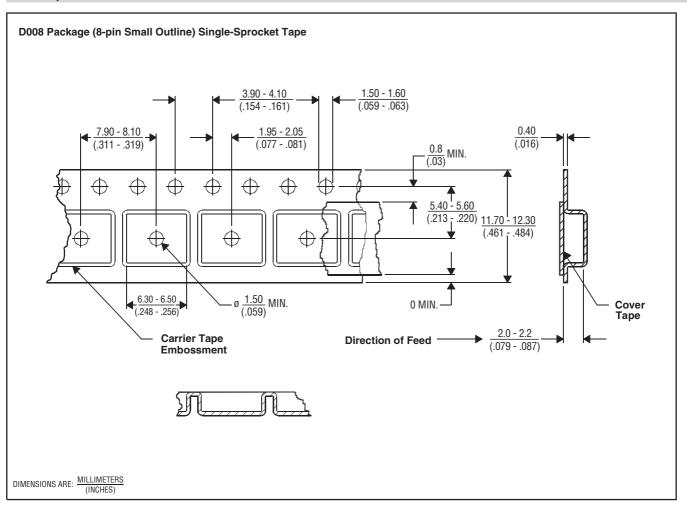
- B. Body dimensions do not include mold flash or protrusion.
- C. Mold flash or protrusion shall not exceed 0.15 (0.006).
- D. Lead tips to be planar within  $\pm 0.051$  (0.002).

# JULY 2000 - REVISED FEBRUARY 2005

# **BOURNS**®

## **MECHANICAL DATA**

## **D008 Tape Dimensions**



NOTES: A. Taped devices are supplied on a reel of the following dimensions:-

MDXXATC

Reel diameter:  $\frac{330 + 0.0/-4.0}{(12.99 + 0.0/-.157)}$ 

Reel hub diameter:  $\frac{100 \pm 2.0}{(3.937 \pm .079)}$ 

Reel axial hole:  $\frac{13.0 \pm 0.2}{(.512 \pm .008)}$ 

B. 2500 devices are on a reel.